

SK15DGD12T7ETE1s



SEMITOP®E1 Solder

3-phase Converter-Inverter-Brake (CIB)

Engineering Sample SK15DGD12T7ETE1s

Target Data

Features*

- Optimized design for superior thermal performance
- Low inductive design
- Solder contact technology
- 1200V Generation 7 IGBT (T7)
- Robust and soft switching CAL4F diode technology
- PEP rectifier diode technology for enhanced power and environmental robustness
- Integrated NTC temperature sensor
- UL recognized file no. E 63 532

Typical Applications

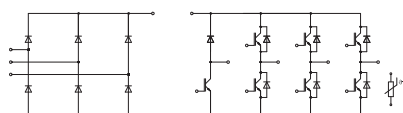
- Motor drives
- Air conditioning
- Auxiliary Inverters

Remarks

- Recommended $T_{j,op} = -40 \dots +150 \text{ }^{\circ}\text{C}$

Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	28	A
	T _j = 175 °C	T _s = 70 °C	22	A
I _C	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	32	A
	T _j = 175 °C	T _s = 70 °C	26	A
I _{Cnom}			15	A
I _{CRM}			30	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 800 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 175 °C	7	μs
T _j			-40 ... 175	°C
Chopper - IGBT				
V _{CES}	T _j = 25 °C		1200	V
I _C	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	28	A
	T _j = 175 °C	T _s = 70 °C	22	A
I _C	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	32	A
	T _j = 175 °C	T _s = 70 °C	26	A
I _{Cnom}			15	A
I _{CRM}			30	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 800 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 175 °C	7	μs
T _j			-40 ... 175	°C
Inverse - Diode				
V _{RRM}	T _j = 25 °C		1200	V
I _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	21	A
	T _j = 175 °C	T _s = 70 °C	17	A
I _F	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	24	A
	T _j = 175 °C	T _s = 70 °C	20	A
I _{FRM}			30	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 150 °C		65	A
T _j			-40 ... 175	°C
Freewheeling - Diode				
V _{RRM}	T _j = 25 °C		1200	V
I _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	15	A
	T _j = 175 °C	T _s = 70 °C	12	A
I _F	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	16	A
	T _j = 175 °C	T _s = 70 °C	13	A
I _{FRM}			20	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 150 °C		36	A
T _j			-40 ... 175	°C



DGDL-ET

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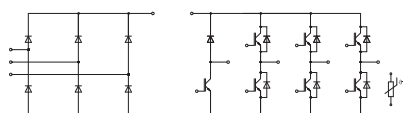
- Recommended $T_{j,op} = -40 \dots +150 \text{ }^{\circ}\text{C}$

Absolute Maximum Ratings

Symbol	Conditions	Values	Unit
Rectifier - Diode			
V_{RRM}	$T_j = 25 \text{ }^{\circ}\text{C}$	1600	V
I_F	$\lambda_{paste} = 0.8 \text{ W/(mK)}$	$T_s = 25 \text{ }^{\circ}\text{C}$	A
	$T_j = 175 \text{ }^{\circ}\text{C}$	$T_s = 70 \text{ }^{\circ}\text{C}$	A
I_F	$\lambda_{paste} = 2.5 \text{ W/(mK)}$	$T_s = 25 \text{ }^{\circ}\text{C}$	A
	$T_j = 175 \text{ }^{\circ}\text{C}$	$T_s = 70 \text{ }^{\circ}\text{C}$	A
I_{FSM}	$t_p = 10 \text{ ms}$	$T_j = 25 \text{ }^{\circ}\text{C}$	A
	$\sin 180^{\circ}$	$T_j = 150 \text{ }^{\circ}\text{C}$	A
i^2t	$t_p = 10 \text{ ms}$	$T_j = 25 \text{ }^{\circ}\text{C}$	A^2s
	$\sin 180^{\circ}$	$T_j = 150 \text{ }^{\circ}\text{C}$	A^2s
T_j		-40 ... 175	$^{\circ}\text{C}$
Module			
$I_{t(RMS)}$	$\Delta T_{terminal}$ at PCB joint = 30 K, per pin	30	A
T_{stg}	module without TIM	-40 ... 125	$^{\circ}\text{C}$
V_{isol}	AC, sinusoidal, 1 min	2500	V

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
V _{CE(sat)}	I _C = 15 A	T _j = 25 °C		1.60	1.75	V
	V _{GE} = 15 V	T _j = 150 °C		1.82	1.96	V
	chiplevel	T _j = 175 °C		1.86	2.00	V
V _{CE0}		T _j = 25 °C		0.90	1.00	V
	chiplevel	T _j = 150 °C		0.75	0.83	V
		T _j = 175 °C		0.72	0.80	V
r _{CE}	V _{GE} = 15 V	T _j = 25 °C		47	50	mΩ
	chiplevel	T _j = 150 °C		71	75	mΩ
		T _j = 175 °C		76	80	mΩ
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 0.33 mA		5.15	5.8	6.45	V
I _{CES}	V _{GE} = 0 V, V _{CE} = 1200 V, T _j = 25 °C				1	mA
C _{ies}	V _{CE} = 25 V	f = 1 MHz		2.8		nF
C _{oes}	V _{GE} = 0 V	f = 1 MHz		0.0364		nF
C _{res}		f = 1 MHz		0.0104		nF
Q _G	V _{GE} = -15V...+15V			207		nC
R _{Gint}	T _j = 25 °C			0		Ω
t _{d(on)}	V _{CC} = 600 V	T _j = 25 °C		31		ns
	I _C = 15 A	T _j = 150 °C		33		ns
	R _{G on} = 7.5 Ω	T _j = 175 °C		35		ns
t _r	R _{G off} = 7.5 Ω	T _j = 25 °C		25		ns
	V _{GE} = +15/-15 V	T _j = 150 °C		27		ns
	(T _j = 150 °C)	T _j = 175 °C		28		ns
E _{on}	di/dt _{on} = 730 A/μs	T _j = 25 °C		0.79		mJ
	di/dt _{off} = 150 A/μs	T _j = 150 °C		1.16		mJ
	dv/dt = 2600 V/μs	T _j = 175 °C		1.31		mJ



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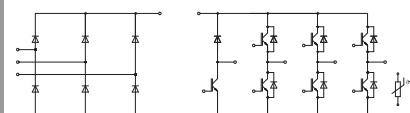
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Remarks

- Recommended $T_{j,op} = -40 \dots +150 \text{ }^{\circ}\text{C}$



DGDL-ET

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
t _{d(off)}	V _{CC} = 600 V	T _j = 25 °C		209		ns
	I _C = 15 A	T _j = 150 °C		254		ns
	R _{G on} = 7.5 Ω	T _j = 175 °C		275		ns
t _f	R _{G off} = 7.5 Ω	T _j = 25 °C		72		ns
	V _{GE} = +15/-15 V	T _j = 150 °C		111		ns
	(T _j = 150 °C)	T _j = 175 °C		119		ns
E _{off}	di/dt _{on} = 730 A/μs	T _j = 25 °C		1.29		mJ
	di/dt _{off} = 150 A/μs	T _j = 150 °C		1.71		mJ
	dv/dt = 2600 V/μs	T _j = 175 °C		1.95		mJ
R _{th(j-s)}	per IGBT, λ _{paste} =0.8 W/(mK)			1.81		K/W
R _{th(j-s)}	per IGBT, λ _{paste} =2.5 W/(mK)			1.43		K/W
Chopper - IGBT						
V _{CE(sat)}	I _C = 15 A	T _j = 25 °C		1.60	1.75	V
	V _{GE} = 15 V	T _j = 150 °C		1.82	1.96	V
	chipelevel	T _j = 175 °C		1.86	2.00	V
V _{CE0}		T _j = 25 °C		0.90	1.00	V
	chipelevel	T _j = 150 °C		0.75	0.83	V
		T _j = 175 °C		0.72	0.80	V
r _{CE}	V _{GE} = 15 V	T _j = 25 °C		47	50	mΩ
	chipelevel	T _j = 150 °C		71	75	mΩ
		T _j = 175 °C		76	80	mΩ
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 0.33 mA		5.15	5.8	6.45	V
I _{CES}	V _{GE} = 0 V, V _{CE} = 1200 V, T _j = 25 °C				1	mA
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		2.8		nF
C _{oes}		f = 1 MHz		0.0364		nF
C _{res}		f = 1 MHz		0.0104		nF
Q _G	V _{GE} = -15V...+15V			207		nC
R _{Gint}	T _j = 25 °C			0		Ω
t _{d(on)}	V _{CC} = 600 V I _C = 15 A R _{G on} = 7.5 Ω R _{G off} = 7.5 Ω V _{GE} = +15/-15 V (T _j = 150 °C) di/dt _{on} = 730 A/μs di/dt _{off} = 150 A/μs dv/dt = 2600 V/μs	T _j = 25 °C		31		ns
		T _j = 150 °C		33		ns
		T _j = 175 °C		35		ns
t _r		T _j = 25 °C		25		ns
		T _j = 150 °C		27		ns
		T _j = 175 °C		28		ns
E _{on}		T _j = 25 °C		0.79		mJ
		T _j = 150 °C		1.16		mJ
		T _j = 175 °C		1.31		mJ
t _{d(off)}		T _j = 25 °C		209		ns
		T _j = 150 °C		254		ns
		T _j = 175 °C		275		ns
t _f		T _j = 25 °C		72		ns
		T _j = 150 °C		111		ns
		T _j = 175 °C		119		ns
E _{off}	T _j = 25 °C		1.29		mJ	
	T _j = 150 °C		1.71		mJ	
	T _j = 175 °C		1.95		mJ	
R _{th(j-s)}	per IGBT, λ _{paste} =0.8 W/(mK)			1.81		K/W
R _{th(j-s)}	per IGBT, λ _{paste} =2.5 W/(mK)			1.43		K/W

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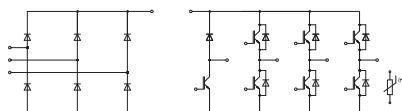
Typical Applications

- Motor drives
- Air conditioning
- Auxiliary Inverters

Remarks

- Recommended $T_{j,op} = -40 \dots +150 \text{ }^{\circ}\text{C}$

Characteristics					
Symbol	Conditions		min.	typ.	max. Unit
Inverse - Diode					
$V_F = V_{EC}$	$I_F = 15 \text{ A}$	$T_j = 25 \text{ }^{\circ}\text{C}$		2.38	2.71 V
		$T_j = 150 \text{ }^{\circ}\text{C}$		2.44	2.77 V
	chiplevel	$T_j = 175 \text{ }^{\circ}\text{C}$		2.26	2.58 V
V_{F0}		$T_j = 25 \text{ }^{\circ}\text{C}$		1.30	1.50 V
	chiplevel	$T_j = 150 \text{ }^{\circ}\text{C}$		0.90	1.10 V
		$T_j = 175 \text{ }^{\circ}\text{C}$		0.82	0.98 V
r_F		$T_j = 25 \text{ }^{\circ}\text{C}$		72	81 mΩ
	chiplevel	$T_j = 150 \text{ }^{\circ}\text{C}$		103	111 mΩ
		$T_j = 175 \text{ }^{\circ}\text{C}$		96	107 mΩ
I_{RRM}		$T_j = 25 \text{ }^{\circ}\text{C}$		11	A
		$T_j = 150 \text{ }^{\circ}\text{C}$		15	A
		$T_j = 175 \text{ }^{\circ}\text{C}$		18	A
Q_{rr}	$V_{CC} = 600 \text{ V}$ $I_F = 15 \text{ A}$	$T_j = 25 \text{ }^{\circ}\text{C}$		1.03	μC
	$V_{GE} = -15 \text{ V}$ ($T_j = 150 \text{ }^{\circ}\text{C}$)	$T_j = 150 \text{ }^{\circ}\text{C}$		2.29	μC
		$T_j = 175 \text{ }^{\circ}\text{C}$		2.58	μC
E_{rr}	$di/dt_{off} = 870 \text{ A/}\mu\text{s}$	$T_j = 25 \text{ }^{\circ}\text{C}$		0.31	mJ
		$T_j = 150 \text{ }^{\circ}\text{C}$		0.97	mJ
		$T_j = 175 \text{ }^{\circ}\text{C}$		1.49	mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 0.8 \text{ W/(mK)}$			2.13	K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 2.5 \text{ W/(mK)}$			1.74	K/W
Freewheeling - Diode					
$V_F = V_{EC}$	$I_F = 10 \text{ A}$	$T_j = 25 \text{ }^{\circ}\text{C}$		2.59	2.94 V
		$T_j = 150 \text{ }^{\circ}\text{C}$		2.71	3.08 V
	chiplevel	$T_j = 175 \text{ }^{\circ}\text{C}$		2.53	2.89 V
V_{F0}		$T_j = 25 \text{ }^{\circ}\text{C}$		1.30	1.50 V
	chiplevel	$T_j = 150 \text{ }^{\circ}\text{C}$		0.90	1.10 V
		$T_j = 175 \text{ }^{\circ}\text{C}$		0.82	0.98 V
r_F		$T_j = 25 \text{ }^{\circ}\text{C}$		129	144 mΩ
	chiplevel	$T_j = 150 \text{ }^{\circ}\text{C}$		181	198 mΩ
		$T_j = 175 \text{ }^{\circ}\text{C}$		171	191 mΩ
I_{RRM}		$T_j = 25 \text{ }^{\circ}\text{C}$		8	A
		$T_j = 150 \text{ }^{\circ}\text{C}$		14	A
		$T_j = 175 \text{ }^{\circ}\text{C}$		16	A
Q_{rr}	$V_{CC} = 600 \text{ V}$ $I_F = 10 \text{ A}$	$T_j = 25 \text{ }^{\circ}\text{C}$		0.58	μC
	$V_{GE} = -15 \text{ V}$ ($T_j = 150 \text{ }^{\circ}\text{C}$)	$T_j = 150 \text{ }^{\circ}\text{C}$		2.01	μC
		$T_j = 175 \text{ }^{\circ}\text{C}$		2.37	μC
E_{rr}	$di/dt_{off} = 790 \text{ A/}\mu\text{s}$	$T_j = 25 \text{ }^{\circ}\text{C}$		0.36	mJ
		$T_j = 150 \text{ }^{\circ}\text{C}$		0.91	mJ
		$T_j = 175 \text{ }^{\circ}\text{C}$		1.16	mJ
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 0.8 \text{ W/(mK)}$			2.64	K/W
$R_{th(j-s)}$	per Diode, $\lambda_{paste} = 2.5 \text{ W/(mK)}$			2.24	K/W



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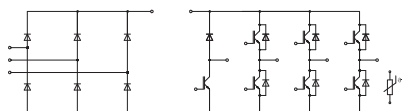
Typical Applications

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Remarks

- Recommended $T_{j,op} = -40 \dots +150 \text{ }^{\circ}\text{C}$

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Rectifier - Diode						
V _F	I _F = 15 A chiplevel	T _j = 25 °C		1.04	1.30	V
		T _j = 150 °C		0.94	1.20	V
		T _j = 175 °C		0.93	1.20	V
V _{F0}	chiplevel	T _j = 25 °C		0.89	1.09	V
		T _j = 150 °C		0.73	0.92	V
		T _j = 175 °C		0.69	0.88	V
r _F	chiplevel	T _j = 25 °C		10	14	mΩ
		T _j = 150 °C		14	19	mΩ
		T _j = 175 °C		16	21	mΩ
I _R	T _j = 150 °C, V _{RRM}				2	mA
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(mK)			1.89		K/W
R _{th(j-s)}	per Diode, λ _{paste} =2.5 W/(mK)			1.52		K/W
Module						
M _s	to heatsink		1.6		2.3	Nm
w				25		g
L _{CE}				30		nH
Temperature Sensor						
R ₁₀₀	T _c =100°C (R ₂₅ =5 kΩ)			493 ± 5%		Ω
B _{25/85}	R(T)=R ₂₅ *exp[B _{25/85} *(1/T-1/298)], T[K]			3420		K



DGD1-ET

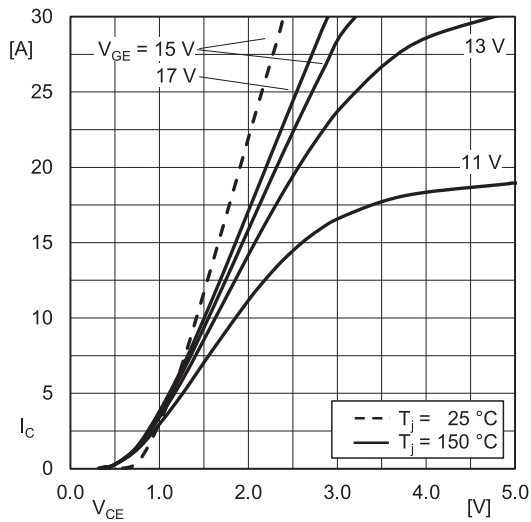


Fig. 1: Typ. IGBT output characteristic, incl. $R_{CC+EE'}$

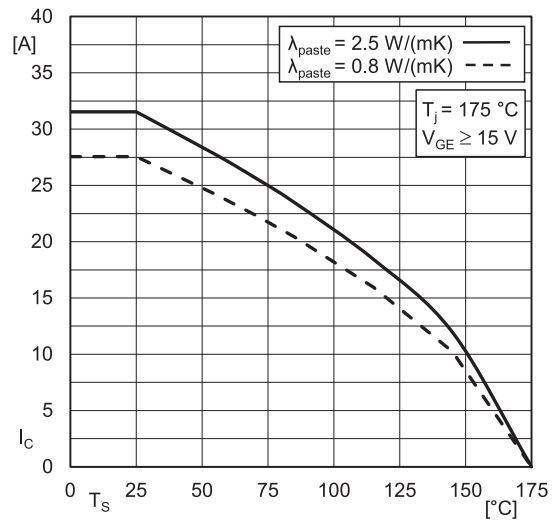


Fig. 2: IGBT rated current vs. temperature $I_C=f(T_s)$

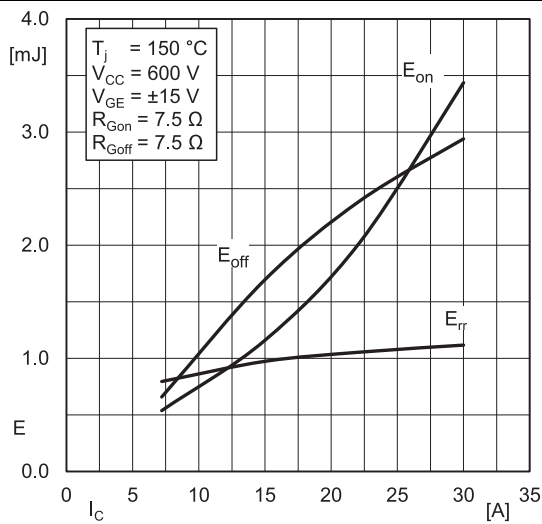


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

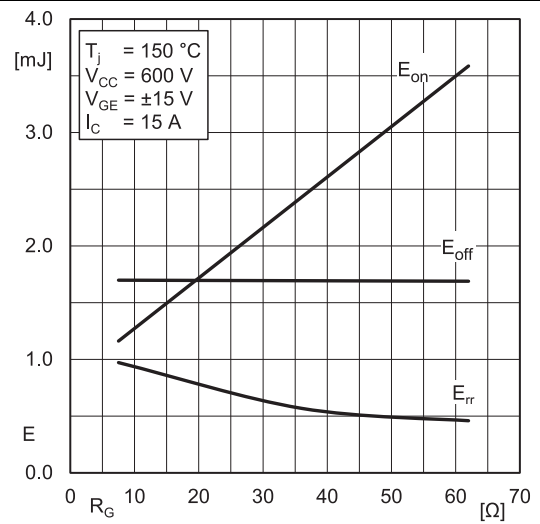


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

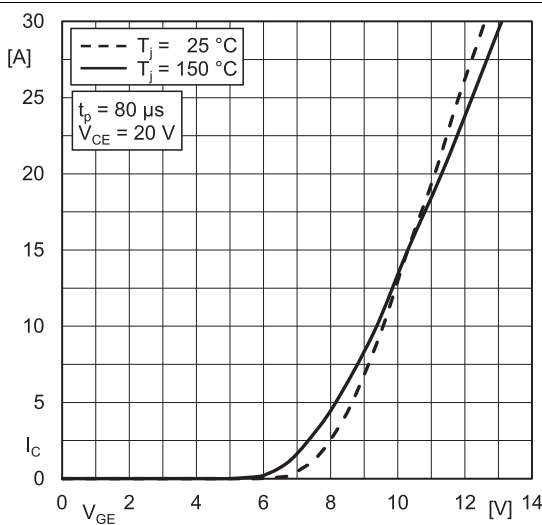


Fig. 5: Typ. IGBT transfer characteristic

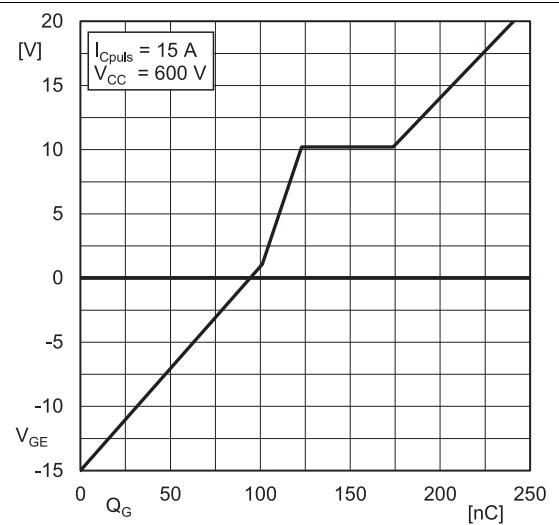


Fig. 6: Typ. IGBT gate charge characteristic

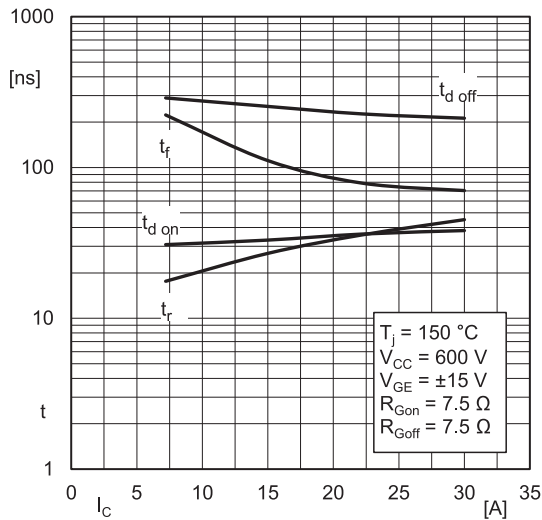


Fig. 7: Typ. switching times = f(I_C)

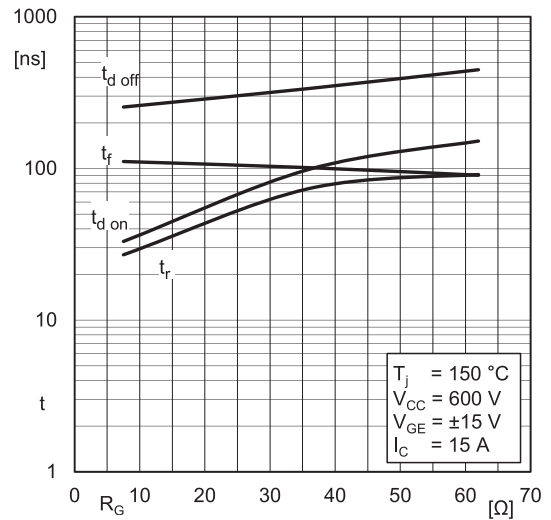


Fig. 8: Typ. switching times = f(R_G)

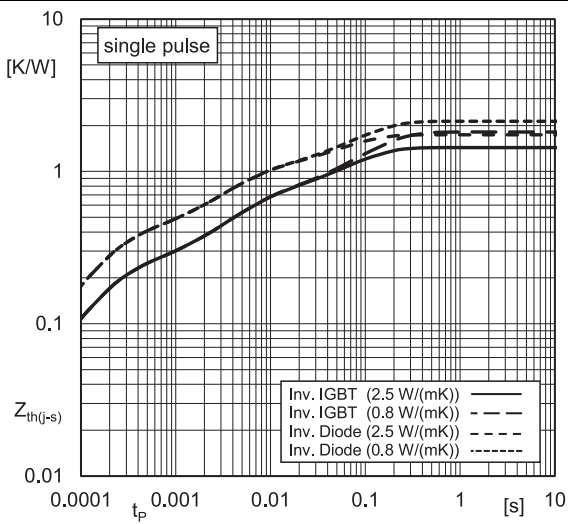


Fig. 9: Typ. transient thermal impedance

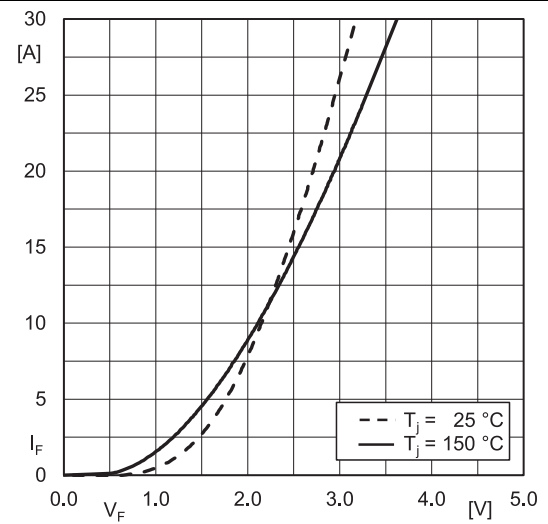


Fig. 10: Typ. Inv. diode forward charact., incl. R_{CC'+EE'}

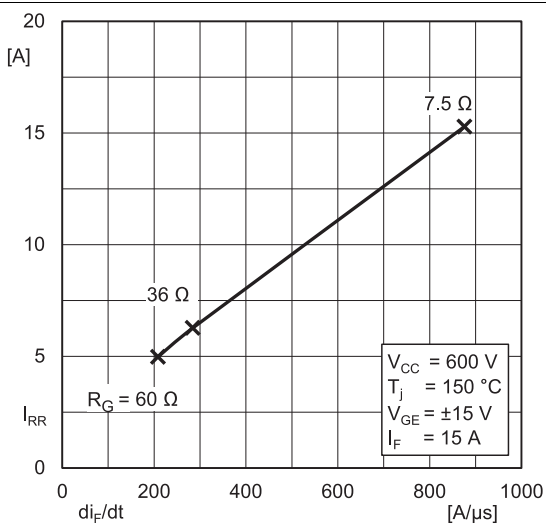


Fig. 11: Typ. Inv. diode peak reverse recovery current

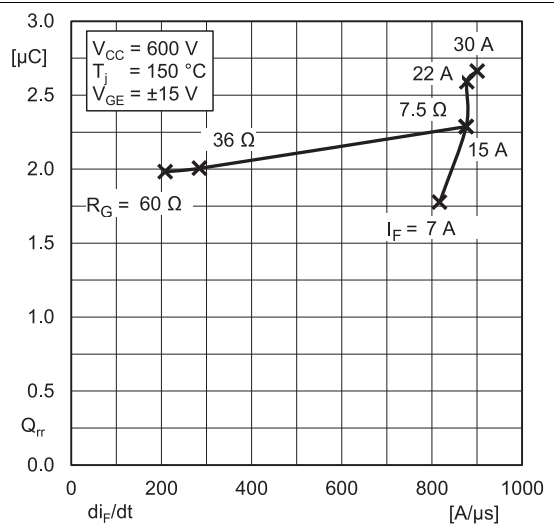


Fig. 12: Typ. Inv. diode reverse recovery charge

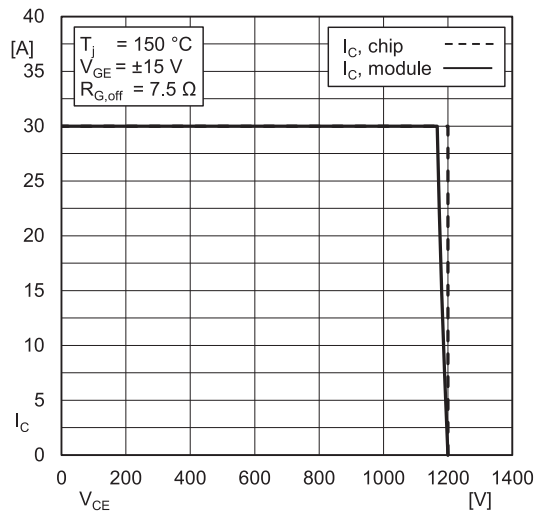


Fig. 13: IGBT Reverse Bias Safe Operating Area (RBSOA)

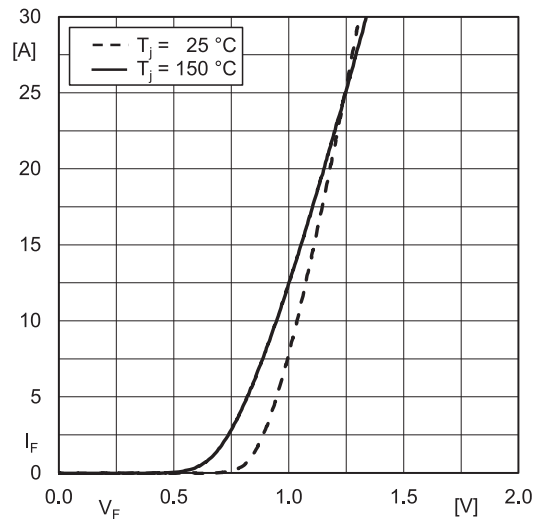
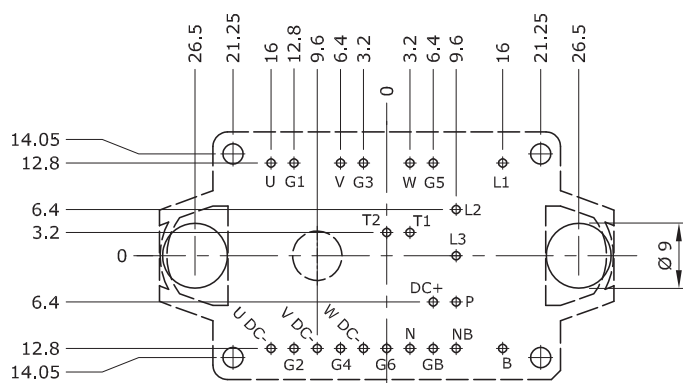
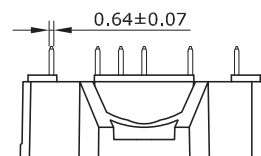
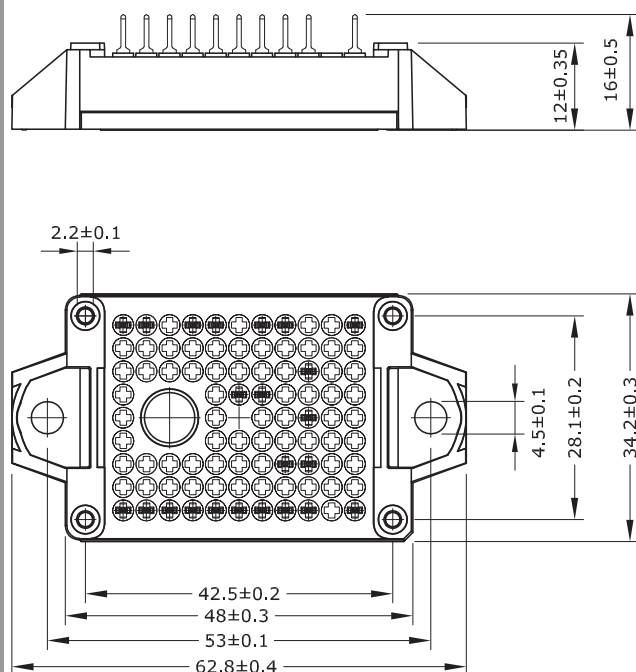


Fig. 14: Typ. Rect. diode forward charact., incl. $R_{CC'+EE'}$

SK15DGDL12T7ETE1s



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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